

SMT Inductor

Material Data Sheet

Product Class	Shielded Power Inductor B82477G4***M000	
Date	07.04.2020	
IMDS ID if available		
Version	11	

Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS** [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
Active Part	Ceramic	4B	Nickel Zinc Ferrite	100	12645-50-0	69.4	
	Heavy Metal	1C	Cu	100	7440-50-8	20.1	
	Elastomer	2B	Polyurethane (PUR)	100	9009-54-5	1.1	
Encapsulation	Duromer	2C	Epoxy (EP)	100	25068-38-6	2.2	
	Woven Material	3A	Polyimide (PI)	100	26298-81-7	0.1	
	Duromer	2C	Acrylic polymer	100	9017-68-9		x
	Duromer	2C	Epoxy resin(EP)	100	25928-94-3	0.2	
	Organic, solid	5B	Quartz	30-50	14808-60-7	0.6	
			Dimethylvinylated and trimethylated silica	15-35	68988-89-6		
			Dimethyl siloxane, dimethylvinyl-terminated	40-60	68083-19-2		
	Organic, solid	5B	Dimethylhydropolysiloxane	100	68037-59-2	0.2	
Heavy Metal	1C	Sn	100	7440-31-5	0.5		
Termination	Heavy Metal	1C	Cu	94	7440-50-8	5.5	
			Sn	6	7440-31-5		
	Heavy Metal	1C	Ni	100	7440-02-0		x
	Heavy Metal	1C	Sn	100	7440-31-5	0.1	
Sum in total:						100	

Size W x L x H [max. in mm]	Weight [approx. in g]	Part Numbers	Size W x L x H [max. in mm]	Weight [approx. in g]	Part Numbers
12.8 x 12.8 x 8.0	4.2	B82477G4xxxM			

Not part of a Product Class		Important remarks: 1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906) Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated. 2) This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.
Contact	Dr. Johann Reindl, MAG EPQM	
Division	TDK Electronics AG, Magnetics Business Group (MAG)	
Address	Rosenheimer Strasse 116b, 81669 Munich	
	Tel: +49 89 54020 3030	mailto: johann.reindl@tdk-electronics.tdk.com
*) others: (not declarable or prohibited substances acc. GADSL)		
**) typical mass percentage of substance		

The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the Product Class / Product according to Annex III: (valid not valid)

no exemptions;

Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;

Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 % lead by weight;

Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;

Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);

Exemption 7 (c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound;

Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;

Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;

Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;

Other Exemption than above

